

# N-Channel Enhancement Mode MOSFET

## 1. Product Information

### 1.1 Features

- Surface-mounted package
- Advanced trench cell design

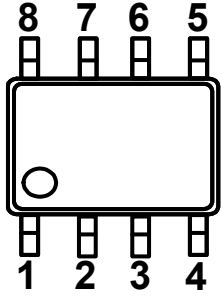
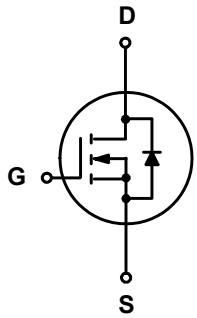
### 1.2 Applications

- Motor appliances
- High power inverter system

### 1.3 Quick reference

- $BV \geq 30\text{ V}$
- $R_{DS(ON)} \leq 18.5\text{ m}\Omega @ V_{GS} = 10\text{ V}$
- $P_{tot} \leq 2\text{ W}$
- $R_{DS(ON)} \leq 21.5\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- $I_D \leq 8\text{ A}$

## 2. Pin Description

Pin	Description	Simplified Outline	Symbol
1,2,3	Source(S)	 Top View SOP- 8L	
4	Gate(G)		
5,6,7,8	Drain(D)		

## 3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	Drain-Source Voltage	T <sub>A</sub> = 25 °C	30	-	V
V <sub>GS</sub>	Gate-Source Voltage	T <sub>A</sub> = 25 °C	-	± 20	V
I <sub>D</sub> *	Drain Current	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = 10 V	-	8	A
		T <sub>A</sub> = 100 °C, V <sub>GS</sub> = 10 V	-	5.3	A
I <sub>DM</sub> **	Pulsed Drain Current	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = 10 V	-	32	A
P <sub>tot</sub>	Total Power Dissipation	T <sub>A</sub> = 25 °C	-	2	W
T <sub>stg</sub>	Storage Temperature		- 55	150	°C
T <sub>J</sub>	Junction Temperature		- 55	150	°C
I <sub>S</sub>	Diode Forward Current	T <sub>A</sub> = 25 °C	-	8	A
R <sub>θJA</sub> *	Thermal Resistance- Junction to Ambient		-	62.5	°C / W

Notes :

\* Surface Mounted on 1 in<sup>2</sup> pad area, t ≤ 10 sec

\*\* Pulse width ≤ 300 μs, duty cycle ≤ 2 %

## 4. Marking Information

Product Name	Marking
KJ4404S	<div style="display: inline-block; border: 1px solid black; padding: 2px;"> <b>4404</b>  <b>YWWXXX</b> </div> <b>YWW:</b> Date Code

## 5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ4404S	SOP8			3000	

Note: KUAJIEXIN defines “ Green ” as lead-free ( RoHS compliant ) and halogen free ( Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC / JEDEC J-STD-020C )

**6. Electrical Characteristics** (  $T_A=25\text{ }^\circ\text{C}$  Unless Otherwise Noted )

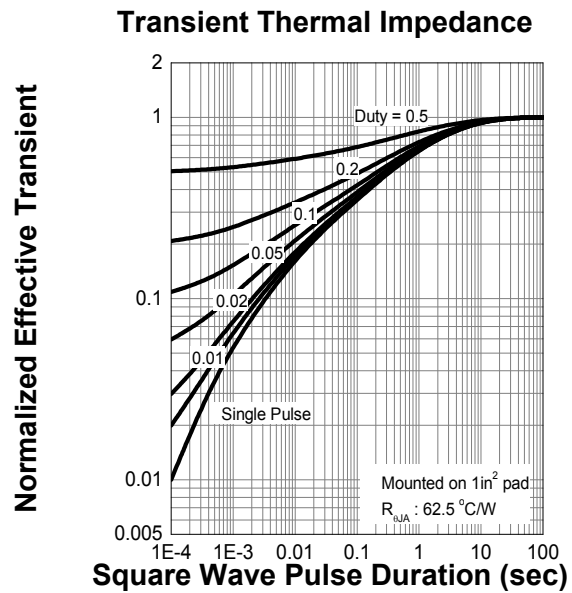
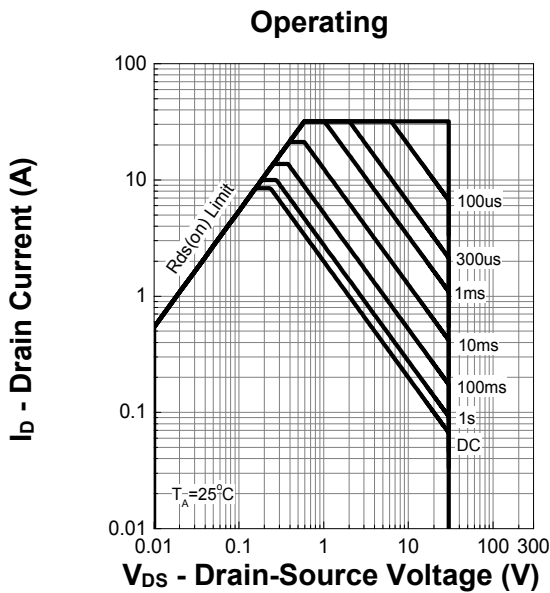
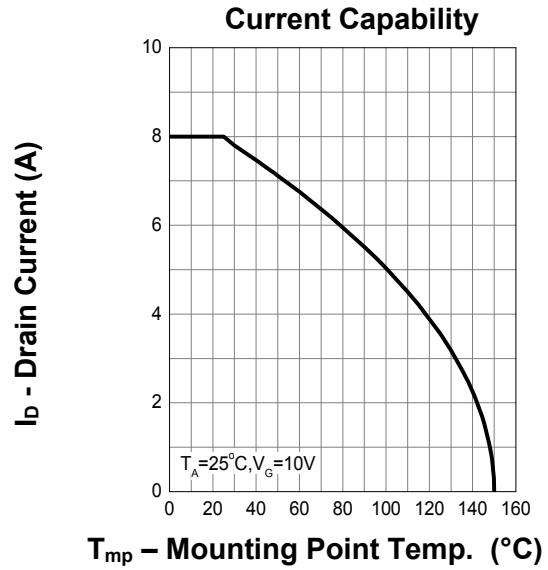
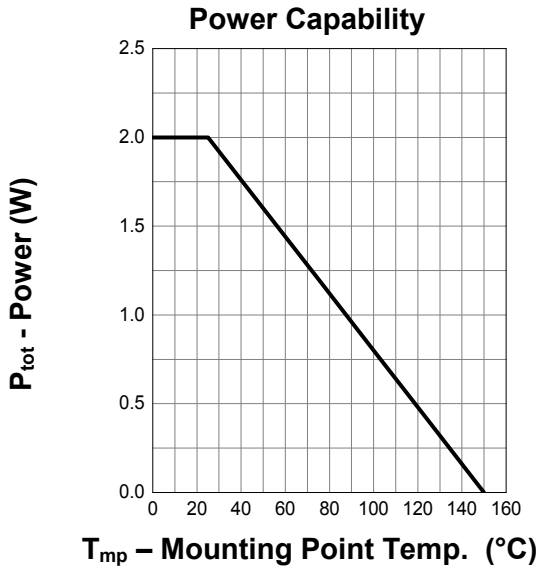
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_{DS} = 250\text{ }\mu\text{A}$	30	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = 250\text{ }\mu\text{A}$	0.5	-	1.0	V
$I_{DSS}$	Drain Leakage Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$T_J = 85\text{ }^\circ\text{C}$	-	-	30	$\mu\text{A}$
$I_{GSS}$	Gate Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	nA
$R_{DS(ON)}^a$	On-State Resistance	$V_{GS} = 10\text{ V}, I_{DS} = 8\text{ A}$	-	14.8	18.5	m $\Omega$
		$V_{GS} = 4.5\text{ V}, I_{DS} = 5\text{ A}$	-	16.5	21.5	
<b>Diode Characteristics</b>						
$V_{SD}^a$	Diode Forward Voltage	$I_{SD} = 8\text{ A}, V_{GS} = 0\text{ V}$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_{DS} = 8\text{ A}, V_{GS} = 0\text{ V}$ $di_{SD}/dt = 100\text{ A}/\mu\text{s}$	-	14	-	nS
$Q_{rr}$	Reverse Recovery Charge		-	6.9	-	$\mu\text{C}$
<b>Dyna10mic Characteristics<sup>b</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 15\text{ V}$ Frequency = 1 MHz	-	630	-	pF
$C_{oss}$	Output Capacitance		-	72	-	
$C_{rss}$	Reverse Transfer Capacitance		-	67	-	
$t_d(on)$	Turn-on Delay Time	$V_{DS} = 15\text{ V}, V_{GEN} = 10\text{ V},$ $R_G = 4.5\text{ }\Omega, R_L = 1.87\text{ }\Omega,$ $I_{DS} = 8\text{ A}$	-	4.6	-	nS
$t_r$	Turn-on Rise Time		-	30	-	
$t_d(off)$	Turn-off Delay Time		-	26	-	
$t_f$	Turn-off Fall Time		-	21	-	
<b>Gate Charge Characteristics<sup>b</sup></b>						
$Q_g$	Total Gate Charge	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V},$ $I_{DS} = 8\text{ A}$	-	21	-	nC
$Q_{gs}$	Gate-Source Charge		-	2	-	
$Q_{gd}$	Gate-Drain Charge		-	3.1	-	

Notes :

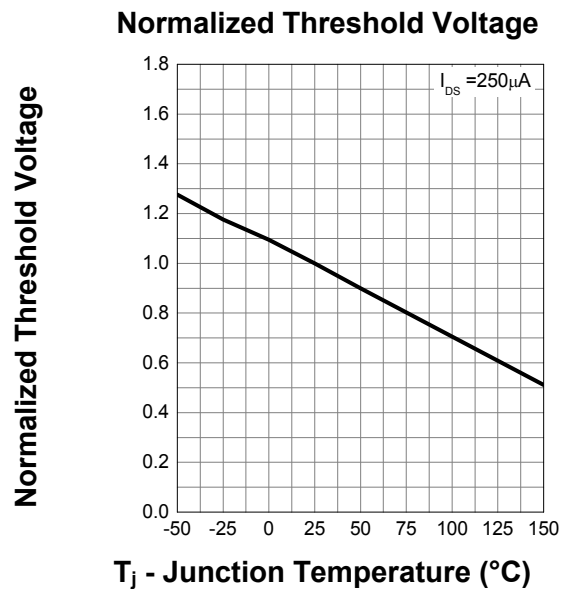
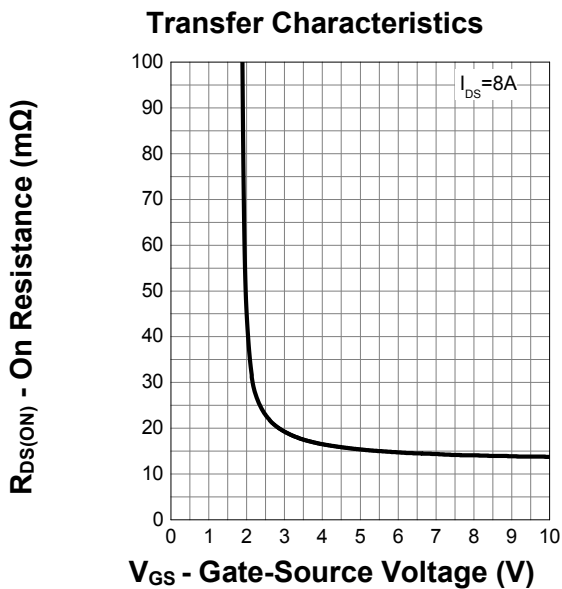
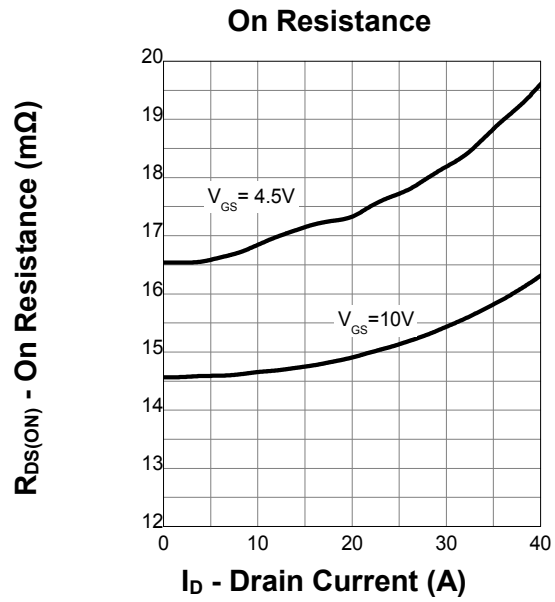
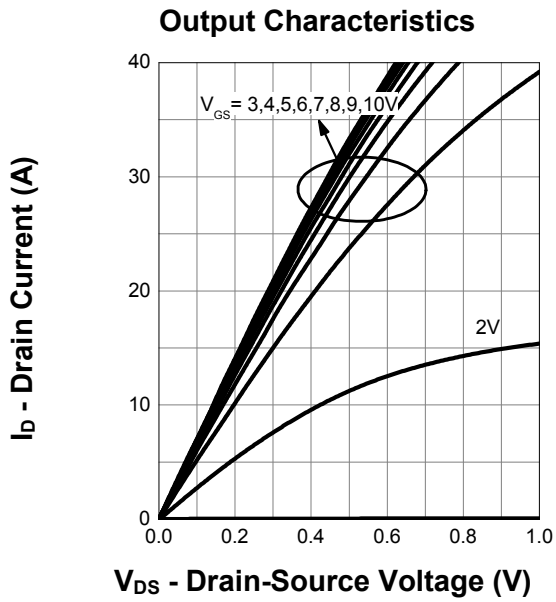
a : Pulse test ; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ 

b : Guaranteed by design, not subject to production testing

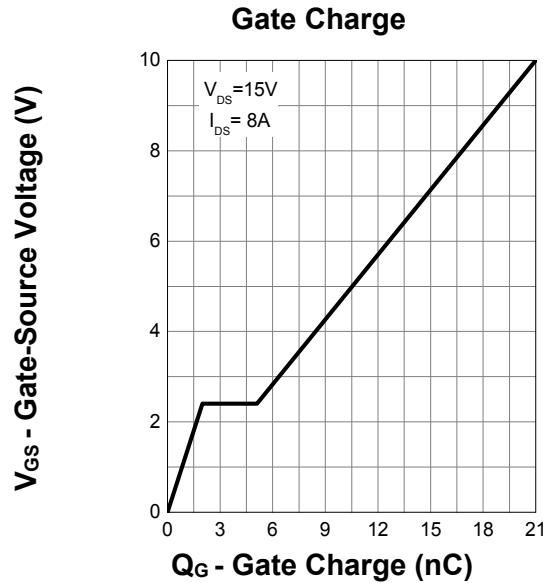
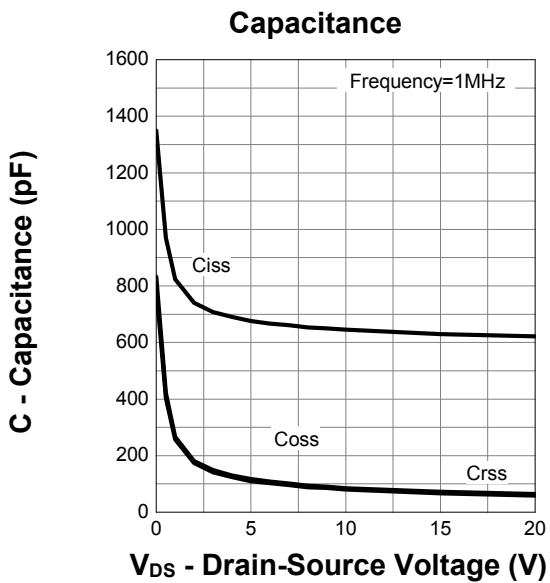
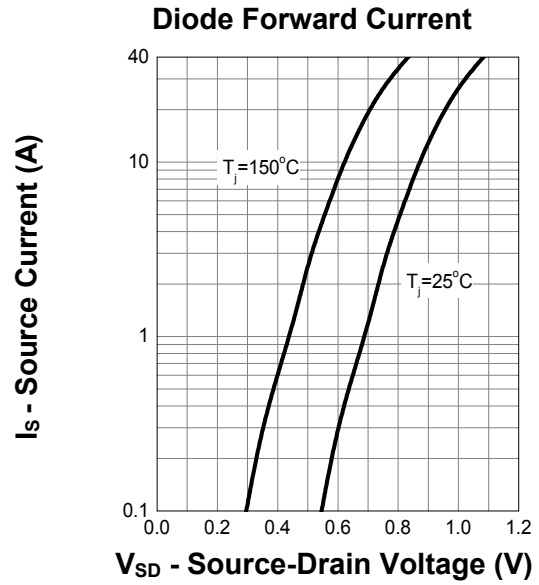
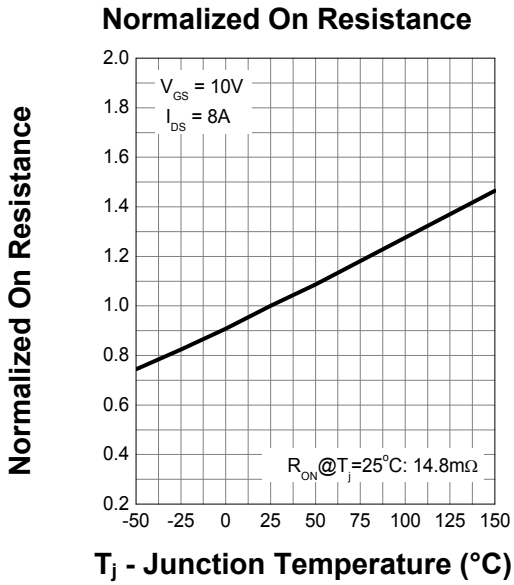
## 7. Typical Characteristics



## 7. Typical Characteristics (cont.)

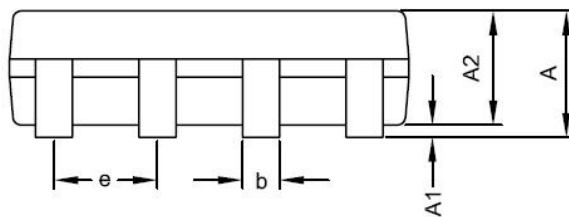
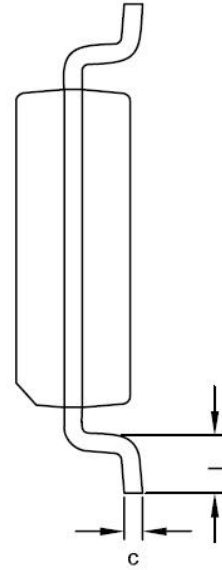
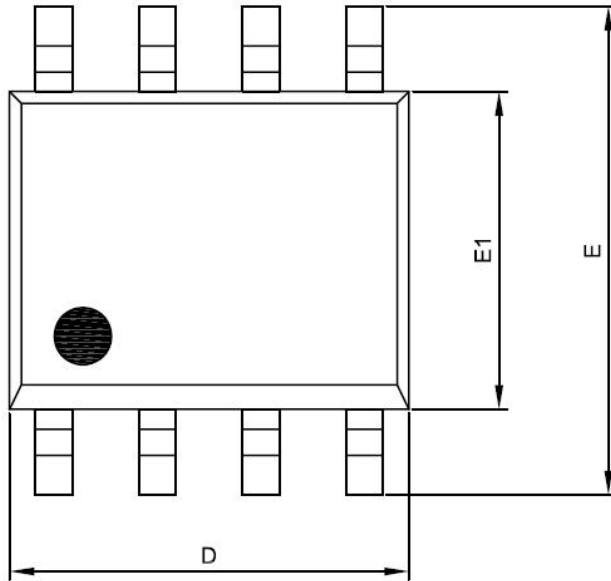


## 7. Typical Characteristics (cont.)



## 8. Package Dimensions

SOP- 8L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	1.35	1.75
A1	0.00	0.25
A2	1.15	1.50
D	4.80	5.00
E	5.80	6.20
E1	3.80	4.00
c	0.19	0.27
b	0.33	0.53
e	1.27 BSC	
L	0.40	1.27

**Notes :**

1. Jedec outline : MS-012AA
2. Dimensions " D " does not include mold flash, protrusions and gate burrs shall not exceed .15 mm (.006 in) per side .
3. Dimensions " E1 " does not include inter-lead flash, or protrusions. Inter-lead flash and protrusions shall not exceed .25 mm (.010 in) per side.